

WHAT IS CLAIMED IS:

1. A solder material wherein a Sn-Zn-Bi alloy containing 0.5 to 10 wt% of zinc and 0.5 to 8 wt% of bismuth, with the balance being substantially tin, is added to with 0.005 to 0.5 wt% of germanium and 0.3 to 3 wt% of copper.
2. A solder material wherein a Sn-Bi-Ag alloy containing 0.5 to 8 wt% of bismuth and 0.5 to 3 wt% of silver, with the balance being substantially tin, is added to with 0.01 to 0.1 wt% of germanium.
3. The solder material as claimed in claim 2 further containing 0.3 to 1 wt% of copper.
4. A solder material wherein a Sn-Zn-In alloy containing 3 to 15 wt% of zinc and 3 to 10 wt% of indium, with the balance being substantially tin, is added to with 0.01 to 0.3 wt% of germanium and 0.3 to 3 wt% of silver.